

Halogen free pin testable solder paste

S3X58-M650-7 Sn 3.0Ag 0.5Cu



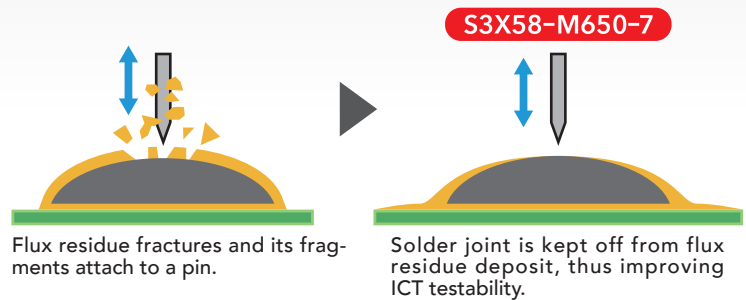
Ease of residue pin testing delivers high inspection accuracy

Inhibits flux residue attachment

Flux residue of conventional solder paste tends to deposit over the solder joint, and could lead to erroneous readings in ICT evaluation even when the assembly itself is flawless.

S3X58-M650-7, on the other hand does all the work that a conventional flux is supposed to do but most importantly prevents the buildup thick and sticky flux residue over the solder joint, which helps the testing probe to get the accurate readings thus improving the first pass yield.

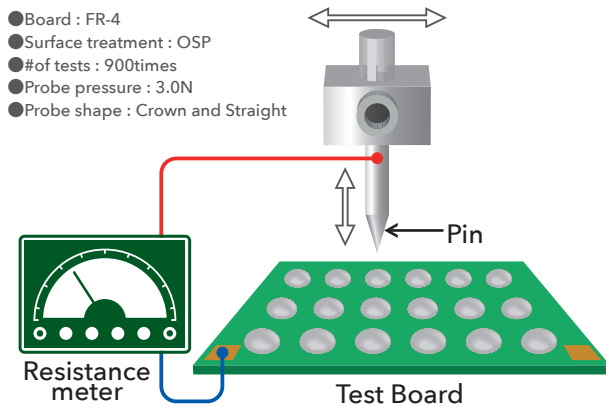
Figure 1. Example of ICT inspection failure



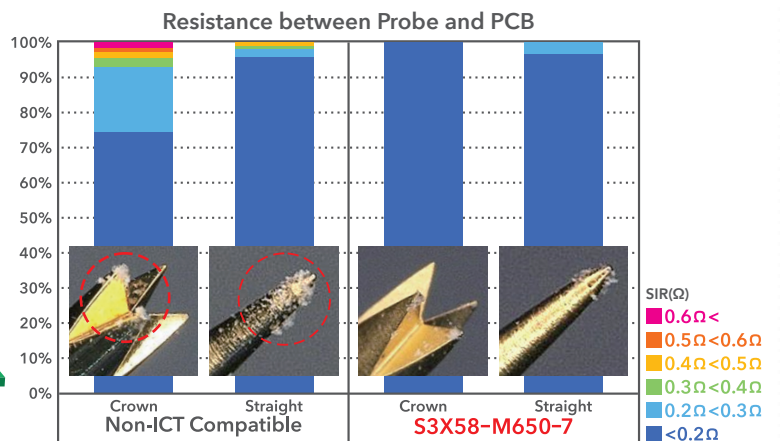
Drastic improvement of pin testability

Securing contact between the testing probe and the solder joint, **S3X58-M650-7** gives consistently high measurement accuracy in ICT evaluation.

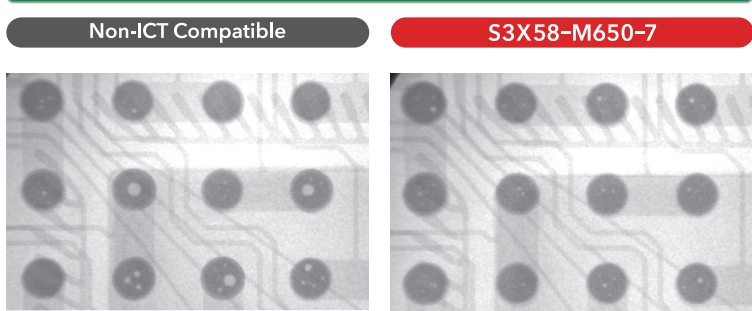
Figure 2. Comparison of pin testability



- Board : FR-4
- Surface treatment : OSP
- #of tests : 900times
- Probe pressure : 3.0N
- Probe shape : Crown and Straight



High meltability reduces voiding



halogen free solder paste

Figure 4. Halogen measurement data

● Test : BS EN14582 *Measured by external institution

Element	Result
Cl	Not detected
Br	Not detected
F	Not detected
I	Not detected

Halogen content (ppm)

Product specifications

Product name	S3X58-M650-7
Alloy composition (%)	Sn 3.0Ag 0.5Cu
Melting point (°C)	217-219
Particle size (μm)	20-38
Viscosity (Pa · s)	200±30
Flux content (%)	11.5±1.0
Halide content (%)	0
Flux type	ROLO

- ICT pin testable
- Anti-pillow defect
- Fine pitch printing >0.4mm pitch >0.3mm dia. CSP
- No clean type
- Halogen Free
- Low voiding
- Tack time >48hr.
- No-clean